

74HC27; 74HCT27

Triple 3-input NOR gate

Rev. 4 — 5 June 2013

Product data sheet

1. General description

The 74HC27; 74HCT27 is a triple 3-input NOR gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Complies with JEDEC standard no. 7A
- Input levels:
 - ◆ For 74HC27: CMOS level
 - ◆ For 74HCT27: TTL level
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to $+85\text{ °C}$ and from -40 °C to $+125\text{ °C}$

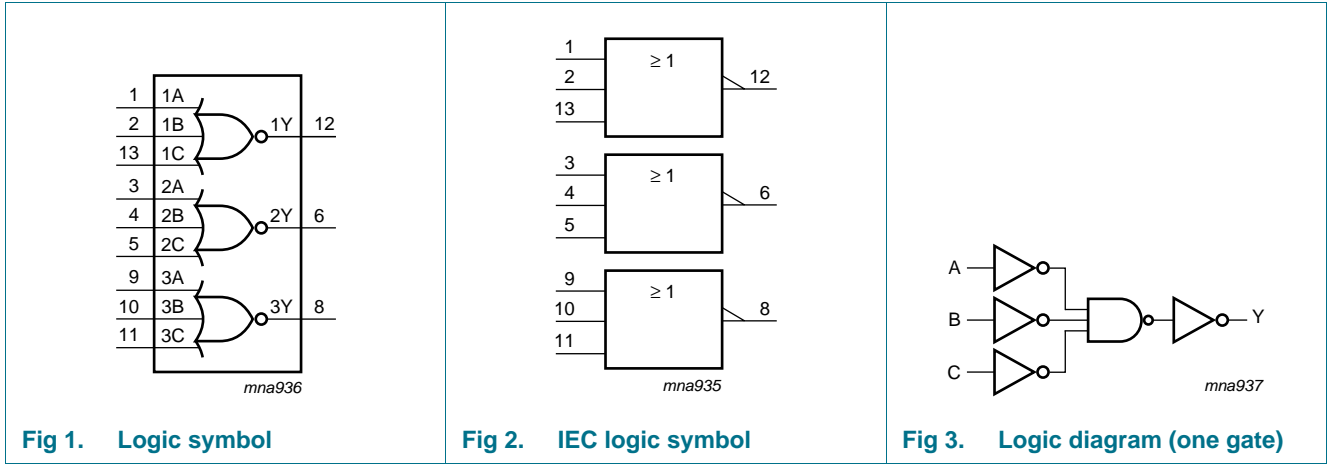
3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|-----------------------|-------------------------------------|----------|-------------------------------------------------------------------------------------------------------------------------------------------------|----------|
| | Temperature range | Name | Description | Version |
| 74HC27N 74HCT27N | -40 °C to $+125\text{ °C}$ | DIP14 | plastic dual in-line package; 14 leads (300 mil) | SOT27-1 |
| 74HC27D 74HCT27D | -40 °C to $+125\text{ °C}$ | SO14 | plastic small outline package; 14 leads; body width 3.9 mm | SOT108-1 |
| 74HC27DB 74HCT27DB | -40 °C to $+125\text{ °C}$ | SSOP14 | plastic shrink small outline package; 14 leads; body width 5.3 mm | SOT337-1 |
| 74HC27PW 74HCT27PW | -40 °C to $+125\text{ °C}$ | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |
| 74HC27BQ 74HCT27BQ | -40 °C to $+125\text{ °C}$ | DHVQFN14 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85\text{ mm}$ | SOT762-1 |

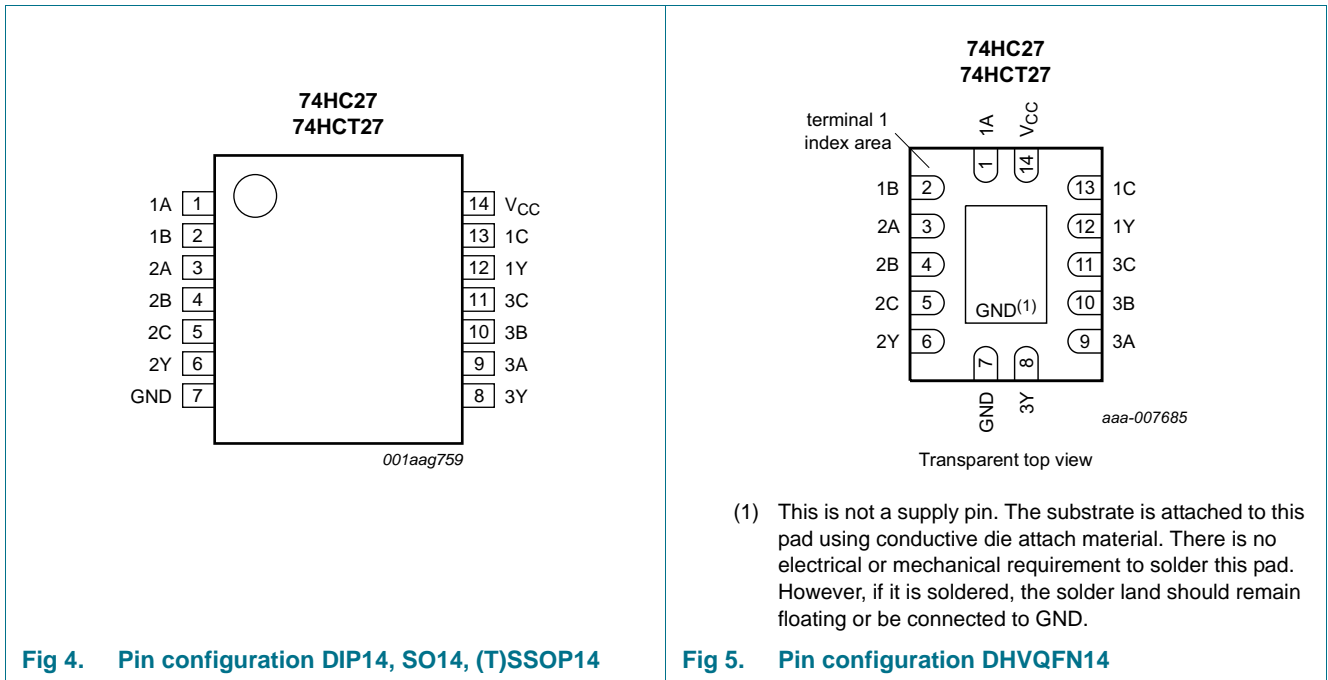


4. Functional diagram



5. Pinning information

5.1 Pinning



(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|-----------|----------------|
| 1A, 2A, 3A | 1, 3, 9 | data input |
| 1B, 2B, 3B | 2, 4, 10 | data input |
| 1C, 2C, 3C | 13, 5, 11 | data input |
| 1Y, 2Y, 3Y | 12, 6, 8 | data output |
| GND | 7 | ground (0 V) |
| V _{CC} | 14 | supply voltage |

6. Functional description

Table 3. Function table^[1]

| Inputs | | | Outputs | |
|--------|----|----|---------|--|
| nA | nB | nC | nY | |
| L | L | L | H | |
| X | X | H | L | |
| X | H | X | L | |
| H | X | X | L | |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|------------------------------------------|--------------------------------------------------------|-------|------|------|
| V _{CC} | supply voltage | | -0.5 | +7 | V |
| I _{IK} | input clamping current | $V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ | [1] - | ±20 | mA |
| I _{OK} | output clamping current | $V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ | [1] - | ±20 | mA |
| I _O | output current | $-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$ | - | ±25 | mA |
| I _{CC} | supply current | | - | 50 | mA |
| I _{GND} | ground current | | -50 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | | [2] | | |
| | DIP14 package | | - | 750 | mW |
| | SO14, (T)SSOP14 and DHVQFN14 packages | | - | 500 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP14 package: P_{tot} derates linearly with 12 mW/K above 70 °C.
 For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
 For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.
 For DHVQFN14 packages: P_{tot} derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

| Symbol | Parameter | Conditions | 74HC27 | | | 74HCT27 | | | Unit |
|------------------|-------------------------------------|-------------------------|--------|------|-----------------|---------|------|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 2.0 V | - | - | 625 | - | - | - | ns/V |
| | | V _{CC} = 4.5 V | - | 1.67 | 139 | - | 1.67 | 139 | ns/V |
| | | V _{CC} = 6.0 V | - | - | 83 | - | - | - | ns/V |

9. Static characteristics

Table 6. Static characteristics type 74HC27; 74HCT27

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|----------------------------------------------------------------------------------------|-------|------|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC27 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | 1.2 | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 4.5 V | 3.15 | 2.4 | - | 3.15 | - | 3.15 | - | V |
| | | V _{CC} = 6.0 V | 4.2 | 3.2 | - | 4.2 | - | 4.2 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | 0.8 | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 4.5 V | - | 2.1 | 1.35 | - | 1.35 | - | 1.35 | V |
| | | V _{CC} = 6.0 V | - | 2.8 | 1.8 | - | 1.8 | - | 1.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| | | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 2.0 | - | 20 | - | 40 | μA |

Table 6. Static characteristics type 74HC27; 74HCT27 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------|-----------|------------------|-----------|-------------------|-----------|---------------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| C_I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |
| 74HCT27 | | | | | | | | | | |
| V_{IH} | HIGH-level input voltage | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | 2.0 | 1.6 | - | 2.0 | - | 2.0 | - | V |
| V_{IL} | LOW-level input voltage | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | - | 1.2 | 0.8 | - | 0.8 | - | 0.8 | V |
| V_{OH} | HIGH-level output voltage | $V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$ | | | | | | | | |
| | | $I_O = -20 \mu\text{A}$ | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | $I_O = -4.0 \text{ mA}$ | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V_{OL} | LOW-level output voltage | $V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$ | | | | | | | | |
| | | $I_O = 20 \mu\text{A}$ | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | $I_O = 4.0 \text{ mA}$ | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| I_I | input leakage current | $V_I = V_{CC} \text{ or } \text{GND}; V_{CC} = 5.5 \text{ V}$ | - | - | ± 0.1 | - | ± 1.0 | - | ± 1.0 | μA |
| I_{CC} | supply current | $V_I = V_{CC} \text{ or } \text{GND}; V_{CC} = 5.5 \text{ V}; I_O = 0 \text{ A}$ | - | - | 2.0 | - | 20 | - | 40 | μA |
| ΔI_{CC} | additional supply current | per input pin; $V_I = V_{CC} - 2.1 \text{ V};$ other inputs at V_{CC} or GND; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V};$ $I_O = 0 \text{ A}$ | | | | | | | | |
| | | nA, nB or nC inputs | - | 150 | 540 | - | 675 | - | 735 | μA |
| C_I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |

10. Dynamic characteristics

Table 7. Dynamic characteristics type 74HC27; 74HCT27

$GND = 0\text{ V}$; for load circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit |
|----------------|-------------------------------|----------------------------------------------------------------------------|-------|-----|-----|-------------------|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| 74HC27 | | | | | | | | |
| t_{pd} | propagation delay | nA, nB, nC to nY; see Figure 6 [1] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 28 | 90 | 115 | 135 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 10 | 18 | 23 | 27 | ns |
| | | $V_{CC} = 5.0\text{ V}; C_L = 15\text{ pF}$ | - | 8 | - | - | - | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 8 | 15 | 20 | 23 | ns |
| t_t | transition time | see Figure 6 [2] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 19 | 75 | 95 | 110 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 7 | 15 | 19 | 22 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 6 | 13 | 16 | 19 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND$ to V_{CC} [3] | - | 24 | - | - | - | pF |
| 74HCT27 | | | | | | | | |
| t_{pd} | propagation delay | nA, nB, nC to nY; see Figure 6 [1] | | | | | | |
| | | $V_{CC} = 4.5\text{ V}$ | - | 12 | 21 | 26 | 32 | ns |
| | | $V_{CC} = 5.0\text{ V}; C_L = 15\text{ pF}$ | - | 10 | - | - | - | ns |
| t_t | transition time | $V_{CC} = 4.5\text{ V}$; see Figure 6 [2] | - | 7 | 15 | 19 | 22 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND$ to $V_{CC} - 1.5\text{ V}$ [3] | - | 30 | - | - | - | pF |

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

[2] t_t is the same as t_{THL} and t_{TLH} .

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

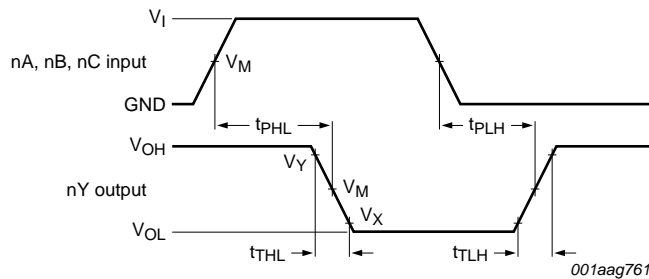
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



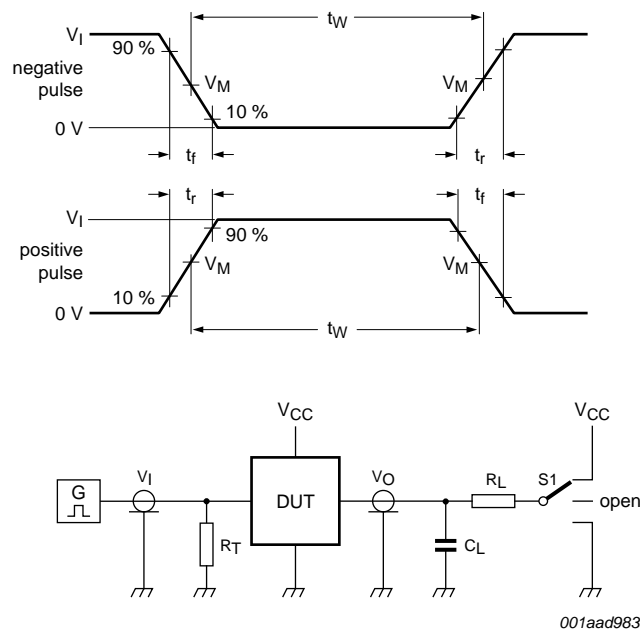
Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output drop that occur with the output load.

Fig 6. Input (nA, nB, nC) to output (nY) propagation delays and output transition times

Table 8. Measurement points

| Type | Input | Output | | |
|---------|-------------|-------------|-------------|-------------|
| | V_M | V_M | V_X | V_Y |
| 74HC27 | $0.5V_{CC}$ | $0.5V_{CC}$ | $0.1V_{CC}$ | $0.9V_{CC}$ |
| 74HCT27 | 1.3 V | 1.3 V | $0.1V_{CC}$ | $0.9V_{CC}$ |



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch

Fig 7. Test circuit for measuring switching times

Table 9. Test data

| Type | Input | | Load | | | S1 position |
|---------|----------|------------|--------------|--------------|--------------------|-------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PHL}, t_{PLH} | |
| 74HC27 | V_{CC} | 6 ns | 15 pF, 50 pF | 1 k Ω | open | |
| 74HCT27 | 3 V | 6 ns | 15 pF, 50 pF | 1 k Ω | open | |

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

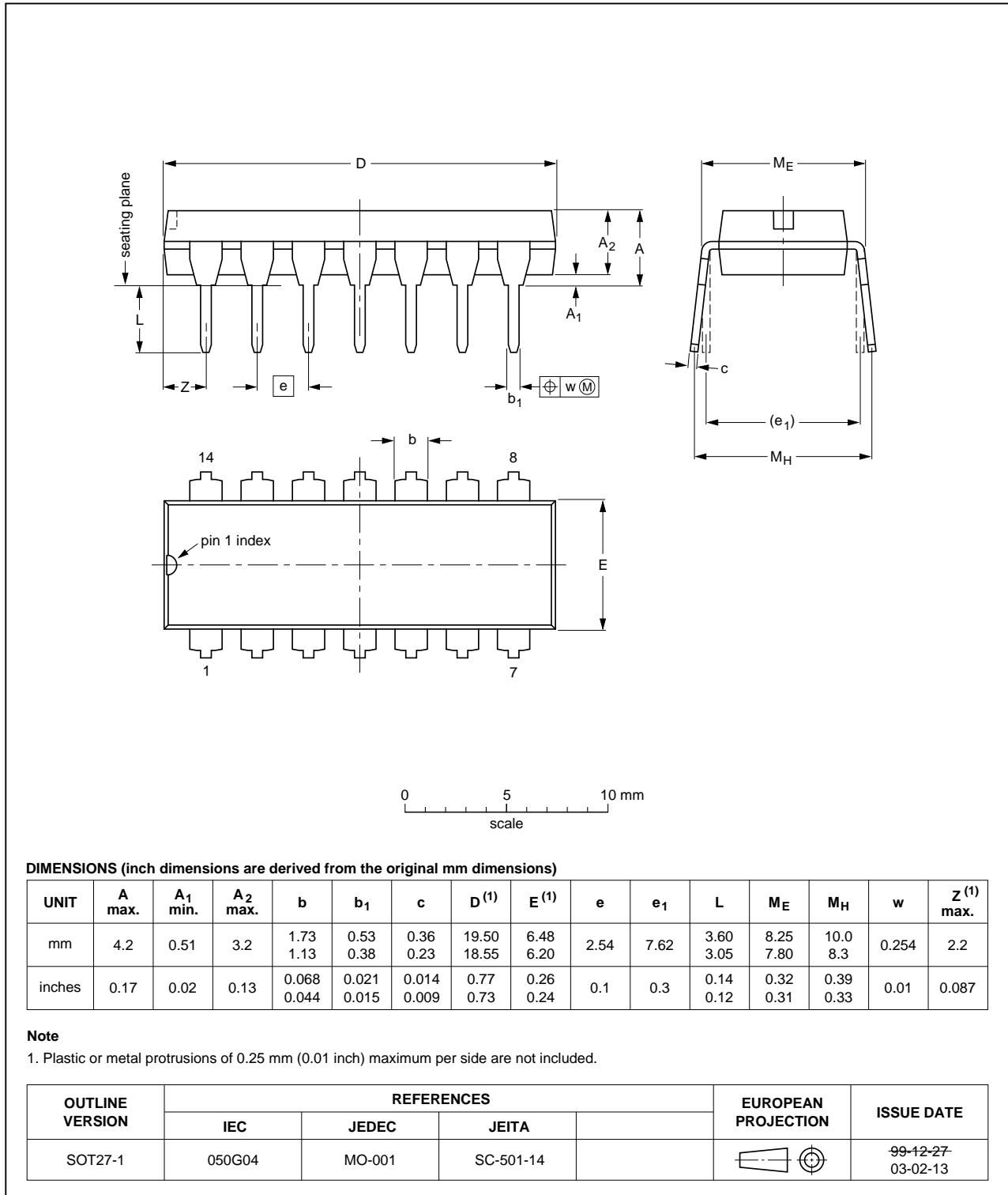


Fig 8. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

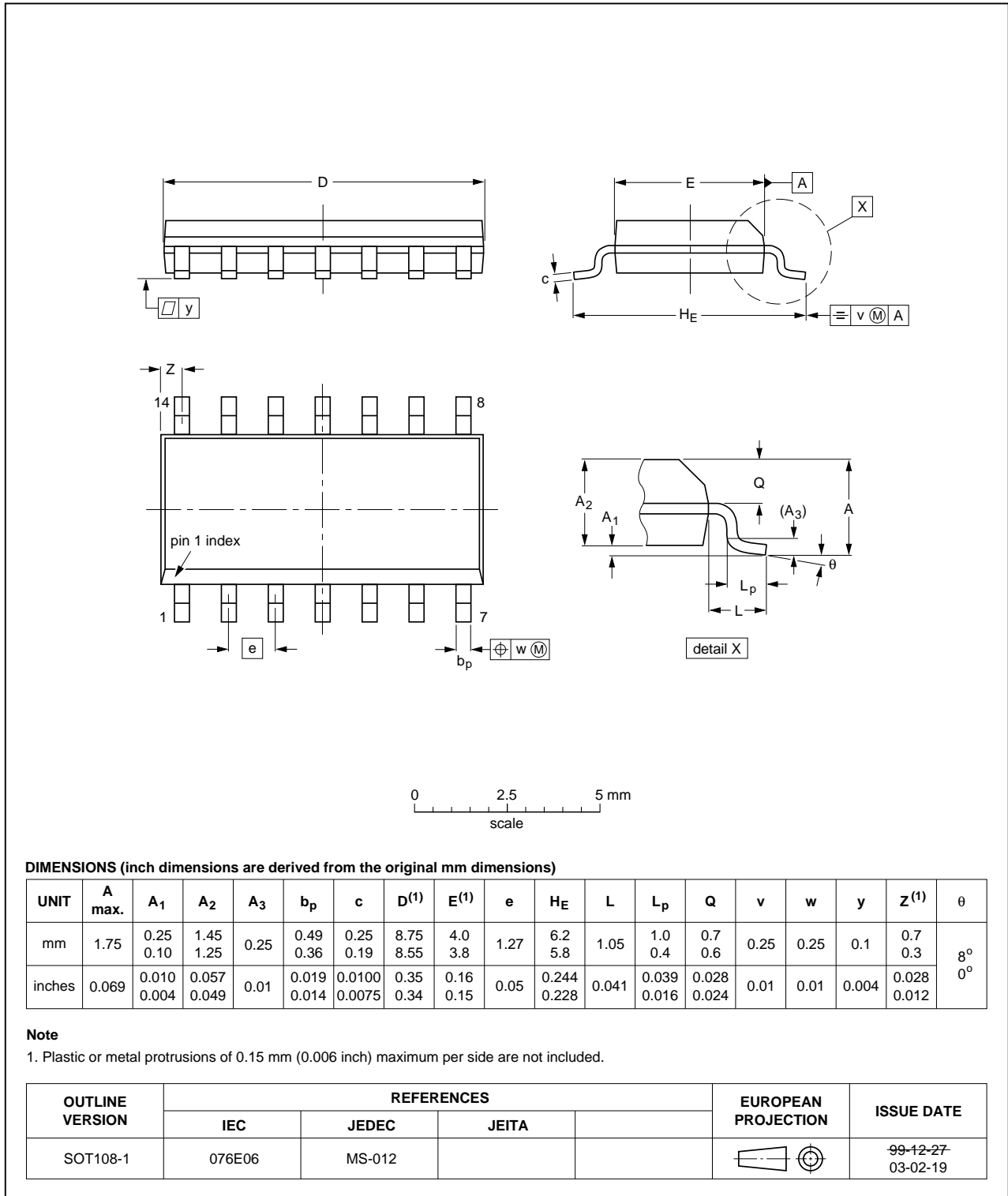


Fig 9. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

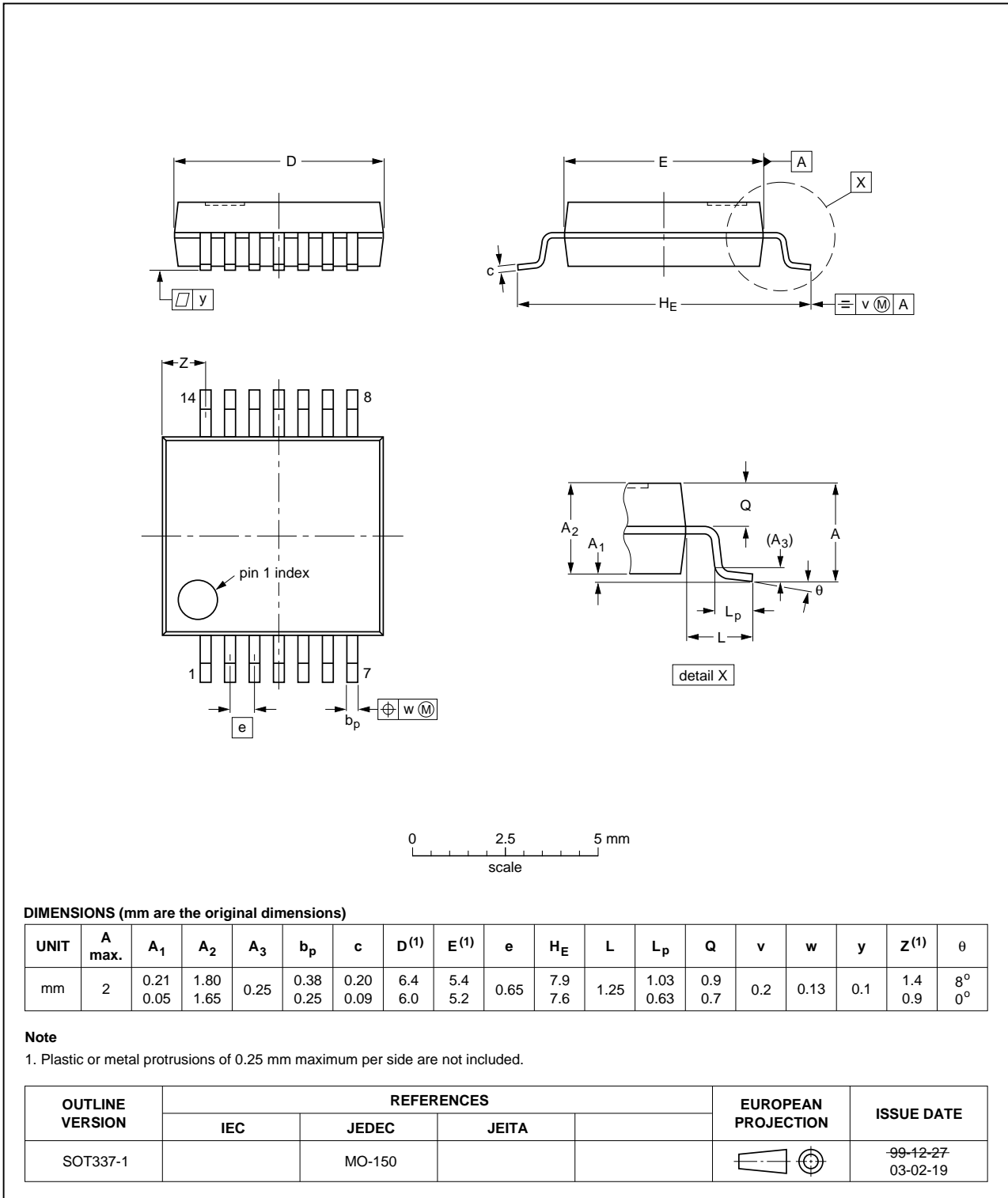


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

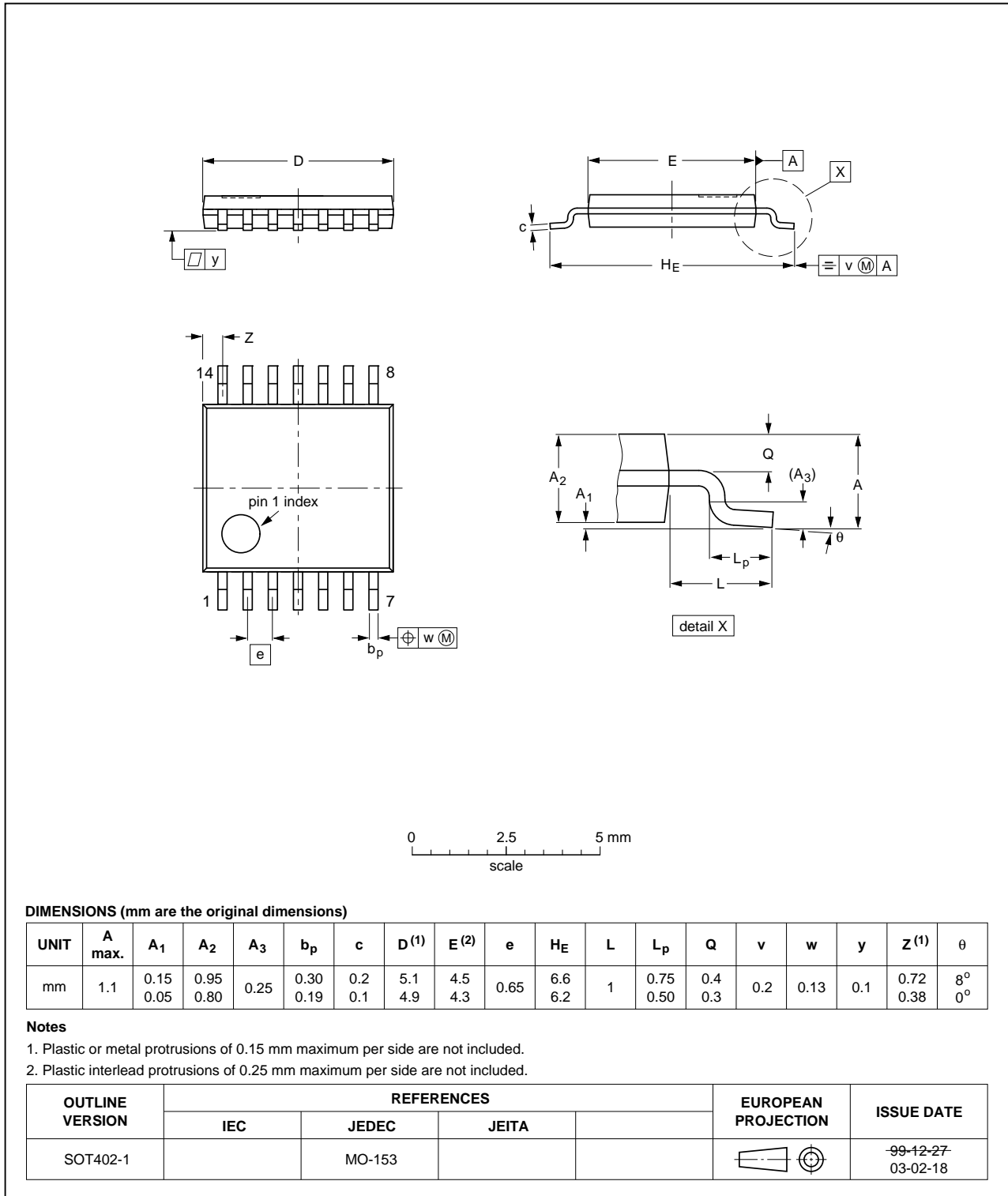


Fig 11. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

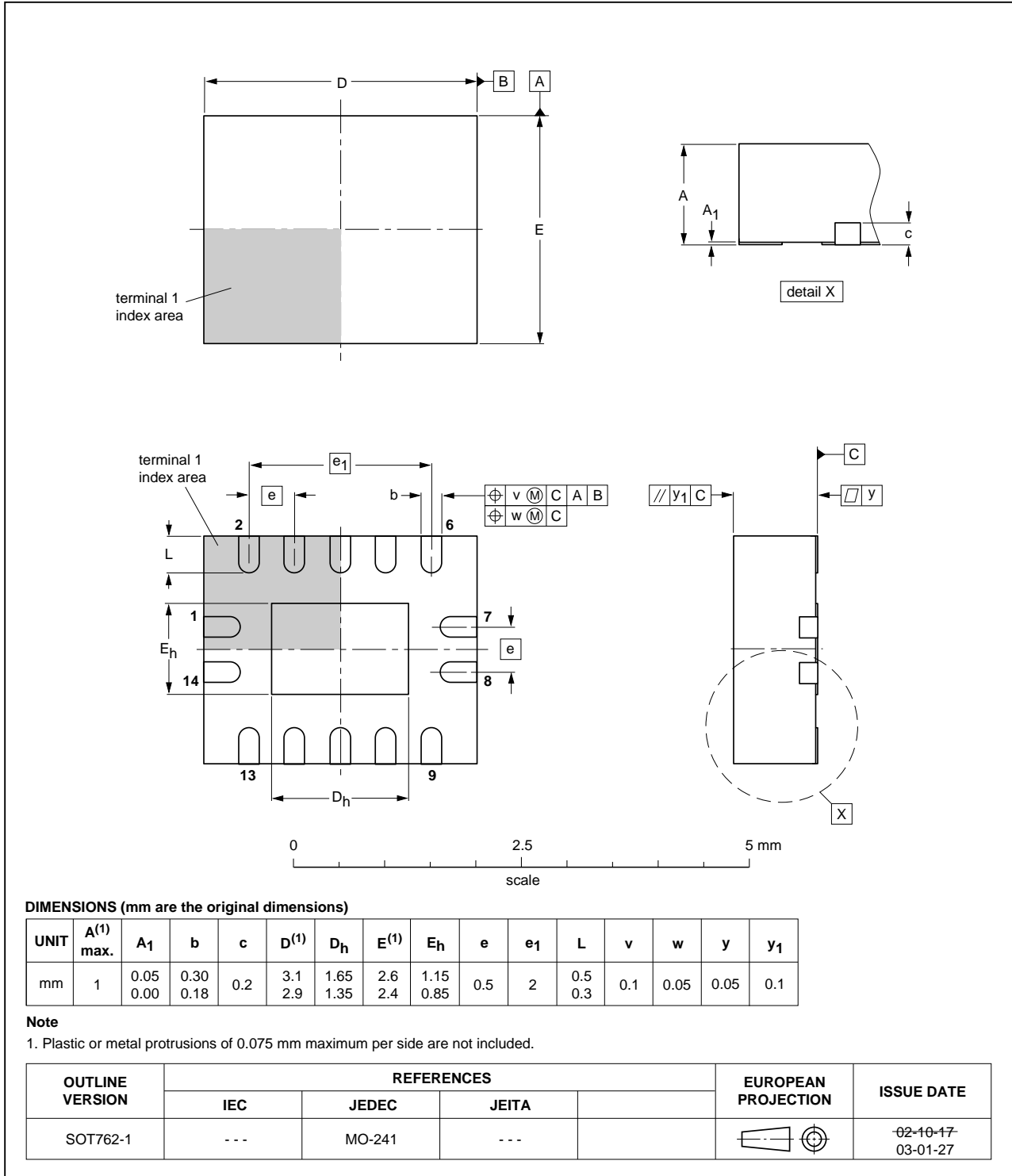


Fig 12. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|-----------------------------------------|
| CMOS | Complementary Metal Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--------------------|--------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------|--------------------|
| 74HC_HCT27 v.4 | 20130605 | Product data sheet | - | 74HC_HCT27 v.3 |
| Modifications: | | <ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate. | | |
| 74HC_HCT27 v.3 | 20080107 | Product data sheet | - | 74HC_HCT27_CNV v.2 |
| 74HC_HCT27_CNV v.2 | 19970828 | Product specification | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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17. Contents

| | | |
|-----------|-----------------------------------------------|-----------|
| 1 | General description | 1 |
| 2 | Features and benefits | 1 |
| 3 | Ordering information | 1 |
| 4 | Functional diagram | 2 |
| 5 | Pinning information | 2 |
| 5.1 | Pinning | 2 |
| 5.2 | Pin description | 3 |
| 6 | Functional description | 3 |
| 7 | Limiting values | 3 |
| 8 | Recommended operating conditions | 4 |
| 9 | Static characteristics | 4 |
| 10 | Dynamic characteristics | 6 |
| 11 | Waveforms | 7 |
| 12 | Package outline | 9 |
| 13 | Abbreviations | 14 |
| 14 | Revision history | 14 |
| 15 | Legal information | 15 |
| 15.1 | Data sheet status | 15 |
| 15.2 | Definitions | 15 |
| 15.3 | Disclaimers | 15 |
| 15.4 | Trademarks | 16 |
| 16 | Contact information | 16 |
| 17 | Contents | 17 |

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